VIGON® A 201

Water-based defluxing agent for spray-in-air cleaning processes

VIGON® A 201 provides excellent cleaning performance in spray-in-air cleaning processes for the cleaning of capillary spaces, e.g. under low standoff components. Used at low concentrations, the MPC®-based cleaning agent VIGON® A 201 is especially suitable for removing flux residues from leaded as well as lead-free No-Clean solder pastes. Its excellent compatibility with sensitive metal alloys leads to shiny solder joints after cleaning without the need for any additives.

Areas of application: PCB cleaning		**Additional product information:**
Low solid flux residues	++	**Technical Information 2**: Overview of all fluxes and solder pastes tested **Technical Information 3**: Material compatibility overview **Application Recommendation**: Specific process parameters for your cleaning trial **MPC® Technology Sheet:** Additional information on MPC® Technology
Rosin based flux residues	++	
Water soluble flux residues	++	
Solder paste (unsoldered)	+	
SMT or conductive adhesives	0	

++ highly recommended, best results + recommended 0 possible - not recommended
* Valid for all standard-, lead-free and lead-based solders

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions

Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:
Phone: +49-841-635-26; Email: techsupport@zestron.com

Advantages compared to other cleaners:

- Successfully cleans under low standoff components such as Micro BGAs, Flip Chips, and 01005 components.
- Especially effective for lead-free No-Clean solder pastes.
- Even at low concentrations and cleaning temperatures, VIGON® A 201 provides excellent cleaning results.
- Leaves shiny solder joints on assemblies after cleaning without any additional additive.
- High bath loading capacity ensures extended bath life, low maintenance costs and reduced costs per cleaned part.
- VIGON® A 201 is easy to rinse and does not leave any residues on the surfaces.
- Does not foam, even in high pressure applications.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.

Process Steps	1. Cleaning	2. Rinsing	3. Drying
Spray-in-air (Inline and Batch)	VIGON® A 201	DI-water	Hot air or circulating air
Centrifugal Cleaning	VIGON® A 201	DI-water	Hot air or circulating air

Technical Data Please note that the information below represents VIGON® A 201 at 15 % concentration.		
Density	(g/ccm) at 20°C/68°F	1
Surface tension	(mN/m) at 25°C/77°F	28.7
Boiling range	°C/°F	> 100 / 212
Flash point	°C/°F	None
pH-value	10g/l H_2O	10.51
Vapor pressure	(mbar) at 20°C/68°F	20
Cleaning temperature	°C/°F	40 – 60 / 104 - 140
Solubility in water		Soluble
Application concentration[1]	%	15 - 20
HMIS Rating	Health-Flammability-Reactivity	1 - 0 - 0

[1] VIGON® A 201 is recommended to be diluted with DI-water only.

PRODUCT FEATURES

Pb lead free	Extensively tested and suitable for cleaning of lead-free solder pastes	MPC	MPC® Technology ensures an extremely long bath life when used in a closed loop system
RoHS WEEE COMPLIANT	100% compliance with EU guidelines (RoHS 1 & 2, WEEE)	REACH	Product is free of any critical substances according to SIN & SVHC lists

Filter recommendation:

- To take full advantage of the MPC® Technology and further expand the bath life of VIGON® A 201, filtration is recommended.
- For details, please request our "Filter Recommendation" sheet.

Environmental, health and safety regulations:

- VIGON® A 201 is water-based and biodegradable.
- The cleaning agent is formulated free of any halogenated compounds.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- VIGON®A 201 is available as concentrate in 1l bottles, 5l or 25l containers and 200l drums.
- Store in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Cleaning Standards:

Electronic assemblies cleaned with VIGON® A 201 in a ZESTRON specified process meet the following industry standards:

- IPC-A-610 Visual cleanliness
- J-STD 001 Ionic and resin cleanliness
- IPC-TM 650 and DIN 32513 (surface resistance)
- J-STD 003 Solderability

ZESTRON
Europe
Ingolstadt–Germany
info@zestron.com
America
Manassas, VA–USA
infousa@zestron.com
South Asia
Kulim–Malaysia
infoasia@zestron.com
North Asia
Shanghai/Shenzhen–China
infochina@zestron.com